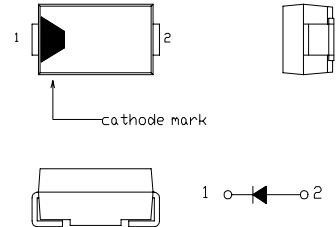


SBD Type : EC31QS09

FEATURES

- * Miniature Size, Surface Mount Device
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight: 0.06g

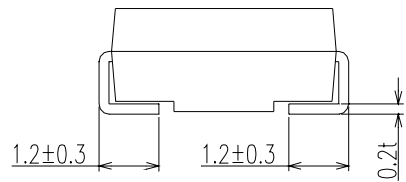
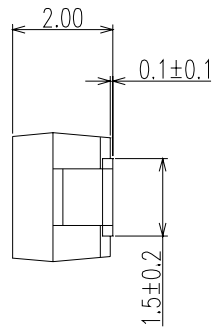
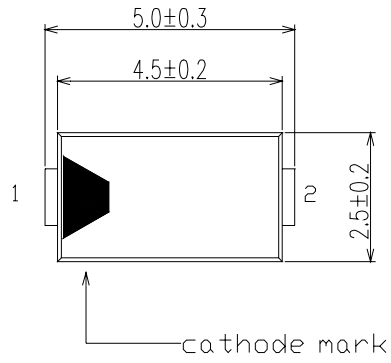
Rating	Symbol	EC31QS09		Unit
Repetitive Peak Reverse Voltage	V_{RRM}	90		V
Average Rectified Output Current	I_O	1.3	$T_a=30\text{ }^\circ\text{C}$ *1	50Hz Half Sine Wave Resistive Load
		3.0	$T_l=85\text{ }^\circ\text{C}$ T_l :Lead Temperature	
RMS Forward Current	$I_{F(RMS)}$	4.71		A
Surge Forward Current	I_{FSM}	60	50Hz Half Sine Wave, 1cycle Non-repetitive	A
Operating Junction Temperature Range	T_{jw}	-40 to +150		$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-40 to +150		$^\circ\text{C}$

Electrical • Thermal Characteristics

Characteristics		Symbol	Conditions	Min.	Typ.	Max.	Unit
Peak Reverse Current		I_{RM}	$T_j=25\text{ }^\circ\text{C}$, $V_{RM}=V_{RRM}$	-	-	2	mA
Peak Forward Voltage		V_{FM}	$T_j=25\text{ }^\circ\text{C}$, $I_{FM}=3.0\text{A}$	-	-	0.85	V
Thermal Resistance	Junction to Ambient	$R_{th(j-a)}$	*1	-	-	108	$^\circ\text{C/W}$
	Junction to Lead	$R_{th(j-l)}$	-	-	-	23	

- *1 Alumina Substrate Mounted
Soldering Lands=2x2mm, Both Sides

EC31QS09 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

